

Article 4 Air pollutants generated by the Semiconductor manufacturing industry shall be gathered by a closed gas gathering system. They may not be discharged until provisions set forth in the following table are observed:

Air pollutant	Target	Emissions Standard
VOCs	Existing process	The discharge reduction rate shall reach 90% or the discharge concentration shall be less than 14 ppm (calculated based on methane).
	Newly established process	The discharge reduction rate shall reach 95% or the discharge concentration shall be less than 10 ppm (calculated based on methane).
Nitric acid, hydrochloric acid, phosphoric acid, hydrofluoric acid and sulfuric acid	Existing process	For each pollutant, the discharge reduction rate shall reach 95% or the discharge concentration shall be less than 0.5 ppm.
	Newly established process	For each pollutant, the discharge reduction rate shall reach 96% or the discharge concentration shall be less than 0.3 ppm.

In the event that the foregoing exhaust gases discharged, including nitric acid, hydrochloric acid, phosphoric acid, hydrofluoric acid,

sulfuric acid, etc., cannot be proved to meet the standard under the preceding paragraph due to safety concerns, relevant documentary evidence shall be submitted to the competent authority of the municipality or county (city) to prove the control conditions with the equivalent or better treatment effect: